



# SIL PAD TSP 3500

Known as SIL-PAD 2000  
November 2018

## PRODUCT DESCRIPTION

Higher Performance, High Reliability Insulator.

<b>Technology</b>	Silicone
Appearance	White
Reinforcement Carrier	Fiberglass
Total Thickness , ASTM D374	0.254 to 0.508mm
<b>Application</b>	Thermal management, Thermally conductive adhesive
Operating Temperature Range	-60 to 200°C

## FEATURES AND BENEFITS

- Thermal impedance: 0.33°C-in<sup>2</sup>/W @ 50 psi
- Optimal heat transfer
- High Thermal Conductivity: 3.5 W/m-K

## TYPICAL APPLICATIONS

- Power supplies
- Motor controls
- Power semiconductors
- Aerospace
- Avionics

SIL PAD TSP 3500 is a high performance, thermally conductive insulator designed for demanding aerospace and commercial applications. SIL PAD TSP 3500 is a silicone elastomer formulated to maximize the thermal and dielectric performance of the filler/binder matrix.

The result is a grease-free, conformable material capable of meeting or exceeding the thermal and electrical requirements of high reliability electronic packaging applications.

## TYPICAL PROPERTIES

### Physical Properties

Hardness, Shore A, ASTM D2240	90
Flammability Rating, UL 94	V-0

### Electrical Properties

Dielectric Breakdown Voltage , ASTM D149, Vac	4,000
Dielectric Constant, ASTM D150 @ 1,000 Hz	4.0
Volume Resistivity, ASTM D257, ohm-meter	1×10 <sup>11</sup>

### Thermal Properties

Thermal Conductivity , ASTM D5470, W/(m-K)	3.5
--	-----



## Thermal Performance vs. Pressure

### TO-220 Thermal Performance

@ 0.01"	
@ 10 psi	2.61
@ 25 psi	2.32
@ 50 psi	2.02
@ 100 psi	1.65
@ 200 psi	1.37

### Thermal Impedance

@ 0.01"	
@ 10 psi	0.57
@ 25 psi	0.43
@ 50 psi	0.33
@ 100 psi	0.25
@ 200 psi	0.2

1) The ASTM D5470 test fixture was used. The recorded value includes interfacial thermal resistance. These values are provided for reference only. Actual application performance is directly related to the surface roughness, flatness and pressure applied.

## GENERAL INFORMATION

For safe handling information on this product, consult the Safety Data Sheet, (SDS).

### Not for product specifications

The technical data contained herein are intended as reference only. Please contact HITEK Electronic Materials for assistance and recommendations on specifications for this product.

## CONFIGURATIONS AVAILABLE

SIL PAD TSP 3500 are supplied in:

- Sheet form and die-cut parts
- With or without pressure-sensitive adhesive

## OUTGASSING INFORMATION

Data for Spacecraft Materials

Post Cure Conditions	%TML (1.0% Max Acceptable)	%CVLM (1.0% Max Acceptable)
24 hours. @175°C	.07	.03
No Post Cure	.26	.10



**Disclaimer****Note:**

The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. The product can have a variety of different applications as well as differing application and working conditions in your environment that are beyond our control. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.

Any liability in respect of the information in the Technical Data Sheet or any other written or oral recommendation(s) regarding the concerned product is excluded, except if otherwise explicitly agreed and except in relation to death or personal injury caused by our negligence and any liability under any applicable mandatory product liability law.

**In case products are delivered by Henkel Belgium NV, Henkel Electronic Materials NV, Henkel Nederland BV, Henkel Technologies France SAS and Henkel France SA please additionally note the following:**

In case Henkel would be nevertheless held liable, on whatever legal ground, Henkel's liability will in no event exceed the amount of the concerned delivery.

**In case products are delivered by Henkel Colombiana, S.A.S. the following disclaimer is applicable:**

The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.

Any liability in respect of the information in the Technical Data Sheet or any other written or oral recommendation(s) regarding the concerned product is excluded, except if otherwise explicitly agreed and except in relation to death or personal injury caused by our negligence and any liability under any applicable mandatory product liability law.

**In case products are delivered by Henkel Corporation, Resin Technology Group, Inc., or Henkel Canada Corporation, the following disclaimer is applicable:**

The data contained herein are furnished for information only and are believed to be reliable. We cannot assume responsibility for the results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any production methods mentioned herein and to adopt such precautions as may be advisable for the protection of property and of persons against any hazards that may be involved in the handling and use thereof. In light of the foregoing, **Henkel Corporation specifically disclaims all warranties expressed or implied, including warranties of merchantability or fitness for a particular purpose, arising from sale or use of Henkel Corporation's products. Henkel Corporation specifically disclaims any liability for consequential or incidental damages of any kind, including lost profits.** The discussion herein of various processes or compositions is not to be interpreted as representation that they are free from domination of patents owned by others or as a license under any Henkel Corporation patents that may cover such processes or compositions. We recommend that each prospective user test his proposed application before repetitive use, using this data as a guide. This product may be covered by one or more United States or foreign patents or patent applications.

**Trademark usage:** [Except as otherwise noted] All trademarks in this document are trademarks and/or registered trademarks of Henkel and its affiliates in the U.S. and elsewhere.

Reference 1

**Conversions**

$$(^{\circ}\text{C} \times 1.8) + 32 = ^{\circ}\text{F}$$

$$\text{kV/mm} \times 25.4 = \text{V/mil}$$

$$\text{mm} / 25.4 = \text{inches}$$

$$\text{N} \times 0.225 = \text{lb}$$

$$\text{N/mm} \times 5.71 = \text{lb/in}$$

$$\text{psi} \times 145 = \text{N/mm}^2$$

$$\text{MPa} = \text{N/mm}^2$$

$$\text{N}\cdot\text{m} \times 8.851 = \text{lb}\cdot\text{in}$$

$$\text{N}\cdot\text{m} \times 0.738 = \text{lb}\cdot\text{ft}$$

$$\text{N}\cdot\text{mm} \times 0.142 = \text{oz}\cdot\text{in}$$

$$\text{mPa}\cdot\text{s} = \text{cP}$$

<p>Supplied by:  <a href="http://www.hitek-ltd.co.uk">www.hitek-ltd.co.uk</a>  +44 (0)1724 851678</p>		<p><b>HITEK</b>  ELECTRONIC MATERIALS LTD</p>
---	---	---

Americas  
+1.888.943.6535

Europe  
+32.1457.5611

Asia  
+86.21.3898.4800

**For the most direct access to local sales and technical support visit: [www.henkel.com](http://www.henkel.com)**